

1st Seminar on New Applications in Nano- and Microtechnology

10 March, 2010



EVG Technology Day

Kazimierzowski Palace, Krakowskie Przedmiescie 26/28

09:00 - 09:10 am	Opening Address
09:10 - 09:40 am	IET activity profile Maciej Bugajski, Piotr Grabiec
09:40 - 09:55 am	EVG corporate profile Gerard Silberer
09:55 - 10:10 am	F&K Delvotec corporate profile Stefan Berger
10:10 - 10:40 am	Coffee Break
10:40 - 11:50 am	Bonding technology Peter Hangweier (Product Manager, EVG)
11:50 am - 01:00 pm	3D integration, thin wafer handling, temporary bonding and debonding Josef Meiler (Regional Sales Director Europe, EVG)
01:00 - 02:00 pm	Lunch
02:00 - 03:05 pm	Automatic bonding and automatic testing - all in one machine Josef Sedlmair (Coordinator Sales & Marketing International, F&K Delvotec)
03:05 - 03:35 pm	Coffee Break
03:35 - 04:40 pm	Advanced lithography and UV-exposure Alois Malzer (Product Manager, EVG)
04:40 - 05:45 pm	Nano-imprint lithography Gerald Kreindl (Product Manager, EVG)
05:45 am -	Closing Address

11 March, 2010



Institute of Electron Technology
Laboratory of Technology of Semiconductor Structures
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09:00 - 12:00 am	<i>Wire Bonder 56xx demonstration</i>
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